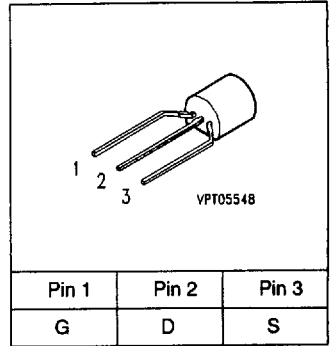


**SIPMOS® Small-Signal Transistor**

- N channel
- Enhancement mode
- Logic Level
- $V_{GS(th)} = 0.8...2.0V$



Type	$V_{DS}$	$I_D$	$R_{DS(on)}$	Package	Marking
BSS 88	240 V	0.25 A	8 $\Omega$	TO-92	SS88

Type	Ordering Code	Tape and Reel Information
BSS 88	Q62702-S287	E6288
BSS 88	Q62702-S303	E6296
BSS 88	Q62702-S576	E6325

**Maximum Ratings**

Parameter	Symbol	Values	Unit
Drain source voltage	$V_{DS}$	240	V
Drain-gate voltage	$V_{DGR}$	240	
$R_{GS} = 20 \text{ k}\Omega$		$\pm 20$	
Gate source voltage	$V_{GS}$	Class 1	
ESD Sensitivity (HBM) as per MIL-STD 883			
Continuous drain current	$I_D$	0.25	A
$T_A = 25 \text{ }^\circ\text{C}$			
DC drain current, pulsed	$I_{Dpuls}$	1	
$T_A = 25 \text{ }^\circ\text{C}$			
Power dissipation	$P_{tot}$	1	W
$T_A = 25 \text{ }^\circ\text{C}$			

**8235605 0133080 041**

**Maximum Ratings**

Parameter	Symbol	Values	Unit
Chip or operating temperature	$T_j$	-55 ... + 150	°C
Storage temperature	$T_{stg}$	-55 ... + 150	
Thermal resistance, chip to ambient air <sup>1)</sup>	$R_{thJA}$	≤ 125	K/W
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

**Static Characteristics**

Drain- source breakdown voltage $V_{GS} = 0\text{ V}$ , $I_D = 0.25\text{ mA}$ , $T_j = 25^\circ\text{C}$	$V_{(BR)DSS}$	240	-	-	V
Gate threshold voltage $V_{GS} = V_{DS}$ , $I_D = 1\text{ mA}$	$V_{GS(th)}$	0.6	0.8	1.2	
Zero gate voltage drain current $V_{DS} = 240\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 25^\circ\text{C}$	$I_{DSS}$	-	0.1	1	μA
$V_{DS} = 240\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 125^\circ\text{C}$		-	10	100	
$V_{DS} = 100\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 25^\circ\text{C}$		-	-	100	nA
Gate-source leakage current $V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$	$I_{GSS}$	-	10	100	nA
Drain-Source on-state resistance $V_{GS} = 4.5\text{ V}$ , $I_D = 0.25\text{ A}$	$R_{DS(on)}$	-	5	8	Ω
$V_{GS} = 1.8\text{ V}$ , $I_D = 14\text{ mA}$		-	7	15	

**■ 8235605 0133081 T88 ■**

**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

**Dynamic Characteristics**

Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}, I_D = 0.25 \text{ A}$	$g_{fs}$	0.14	0.31	-	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	$C_{iss}$	-	80	110	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	$C_{oss}$	-	15	25	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	$C_{rss}$	-	8	12	
Turn-on delay time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 0.28 \text{ A}$ $R_G = 50 \ \Omega$	$t_{d(on)}$	-	5	8	ns
Rise time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 0.28 \text{ A}$ $R_G = 50 \ \Omega$	$t_r$	-	10	15	
Turn-off delay time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 0.28 \text{ A}$ $R_G = 50 \ \Omega$	$t_{d(off)}$	-	30	40	
Fall time $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 0.28 \text{ A}$ $R_G = 50 \ \Omega$	$t_f$	-	25	35	

**■ 8235605 0133082 914 ■**

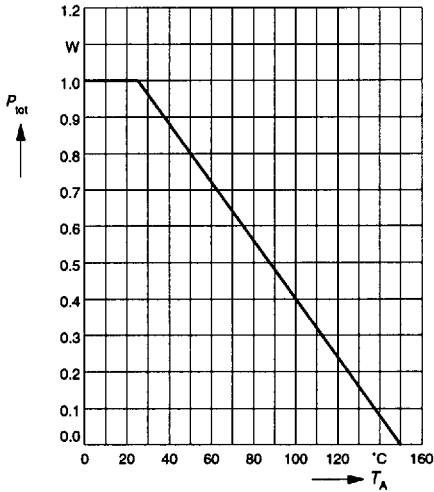
**Electrical Characteristics, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Inverse diode continuous forward current $T_A = 25^\circ\text{C}$	$I_S$	-	-	0.25	A
Inverse diode direct current, pulsed $T_A = 25^\circ\text{C}$	$I_{SM}$	-	-	1	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = 0.5\text{ A}$	$V_{SD}$	-	0.9	1.3	V

■ 8235605 0133083 850 ■

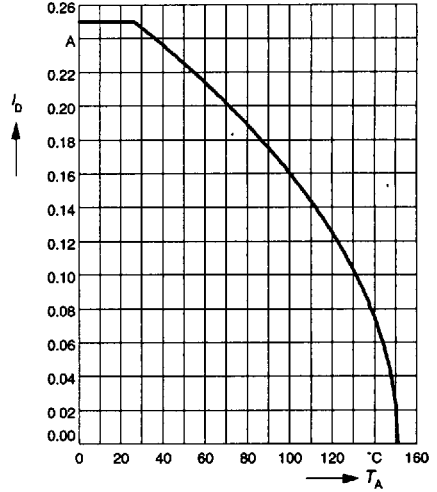
**Power dissipation**

$P_{tot} = f(T_A)$



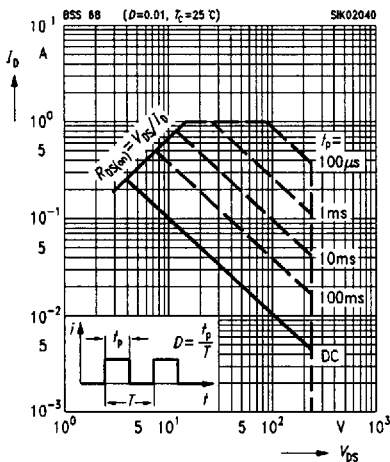
**Drain current**

$I_D = f(T_A)$   
parameter:  $V_{GS} \geq 4 \text{ V}$



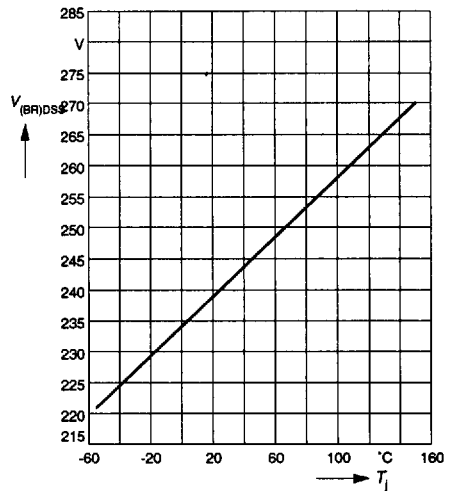
**Safe operating area  $I_D = f(V_{DS})$**

parameter:  $D = 0.01, T_C = 25^\circ\text{C}$



**Drain-source breakdown voltage**

$V_{(BR)DSS} = f(T_J)$

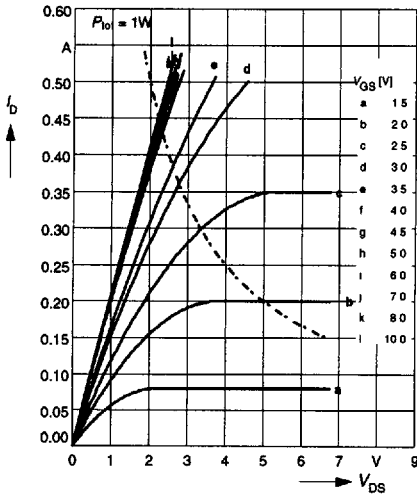


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**Typ. output characteristics**

$I_D = f(V_{DS})$

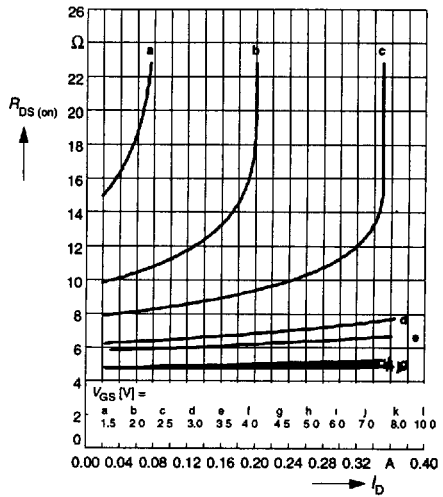
parameter:  $t_p = 80 \mu s$



**Typ. drain-source on-resistance**

$R_{DS(on)} = f(I_D)$

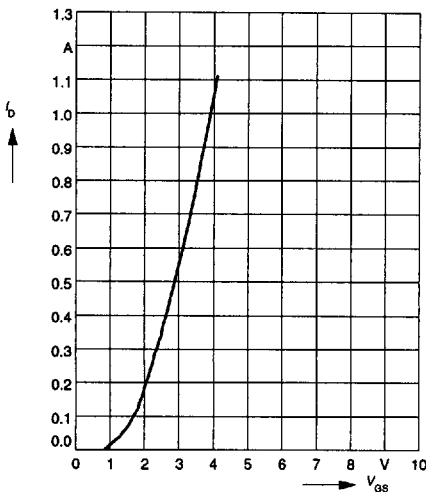
parameter:  $t_p = 80 \mu s, T_j = 25 \text{ }^\circ\text{C}$



**Typ. transfer characteristics**  $I_D = f(V_{GS})$

parameter:  $t_p = 80 \mu s$

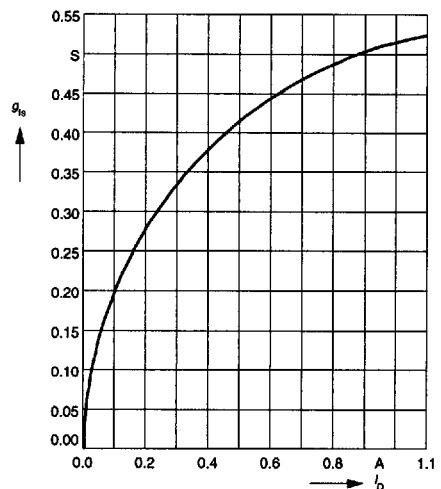
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



**Typ. forward transconductance**  $g_{fs} = f(I_D)$

parameter:  $t_p = 80 \mu s,$

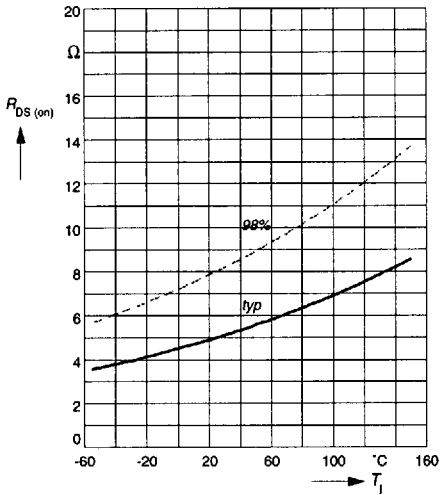
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



**Drain-source on-resistance**

$$R_{DS(on)} = f(T_J)$$

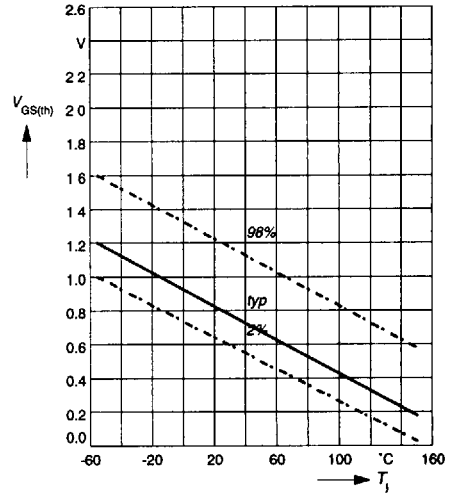
parameter:  $I_D = 0.25\text{ A}$ ,  $V_{GS} = 4.5\text{ V}$



**Gate threshold voltage**

$$V_{GS(th)} = f(T_J)$$

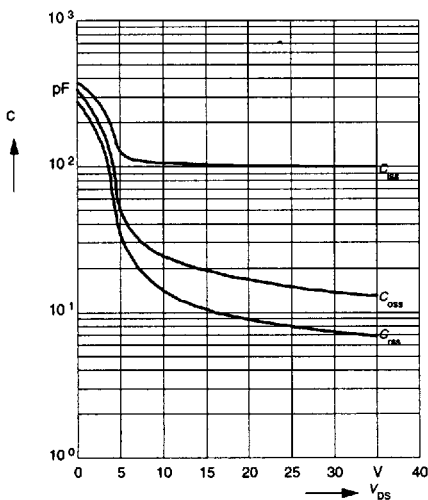
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 1\text{ mA}$



**Typ. capacitances**

$$C = f(V_{DS})$$

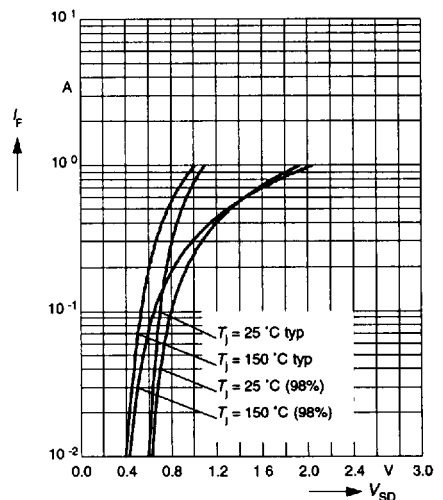
parameter:  $V_{GS} = 0\text{ V}$ ,  $f = 1\text{ MHz}$



**Forward characteristics of reverse diode**

$$I_F = f(V_{SD})$$

parameter:  $T_J$ ,  $t_p = 80\ \mu\text{s}$

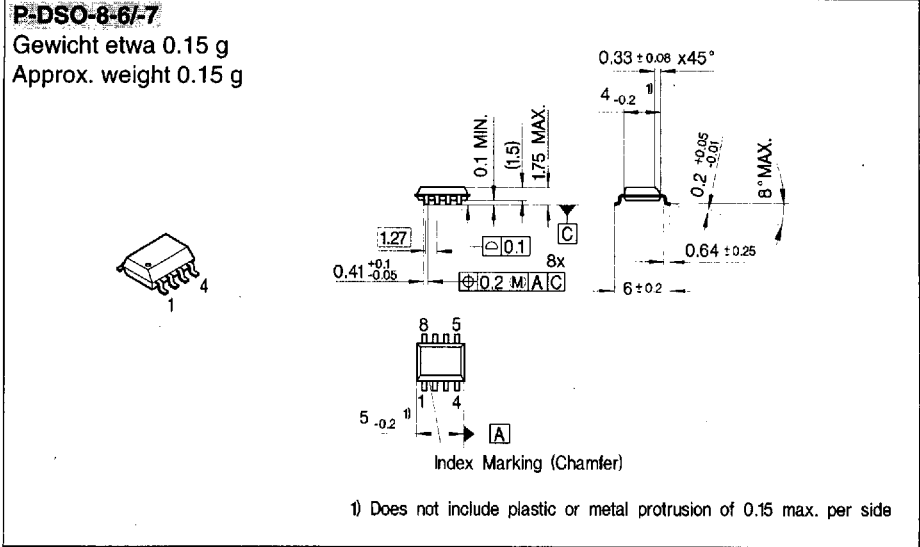


**Gehäusemaßbilder**

(Maße in mm, wenn nicht anders angegeben)

**Package Outlines**

(Dimensions in mm, unless otherwise specified)



**Bild 16**

**Figure 16**

**P-TO218-AA (P-TO218-2-1)**

Gewicht etwa 4.9 g  
Approx. weight 4.9 g

**Bild 17**

**Figure 17**



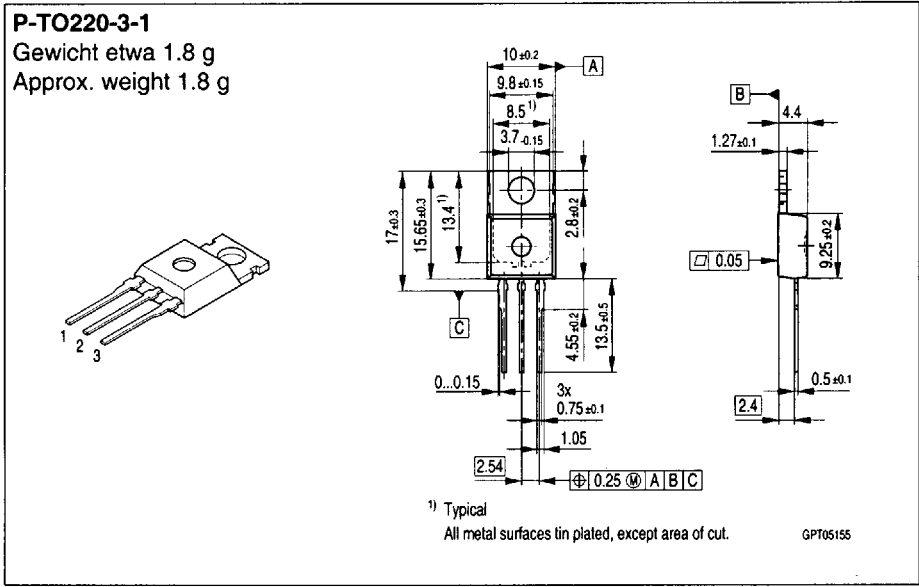


Bild 18

Figure 18

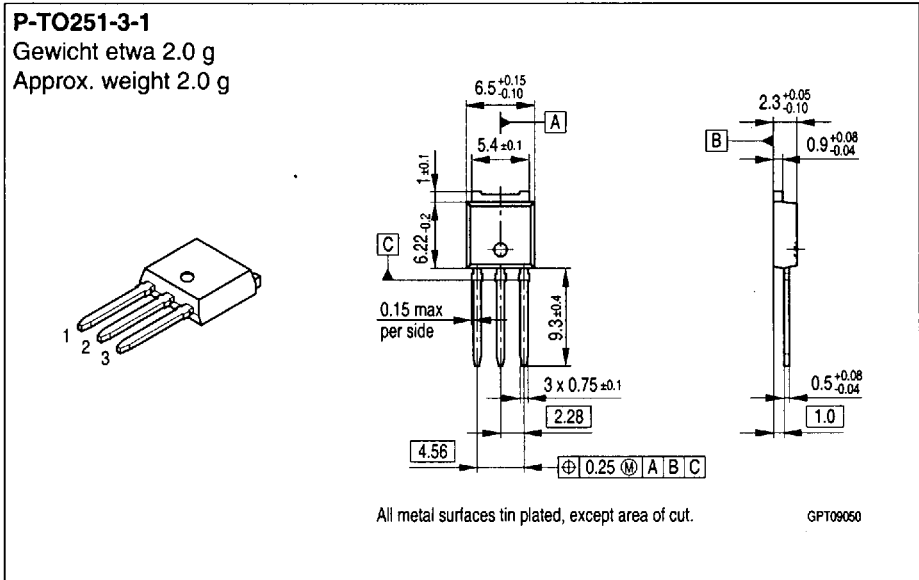
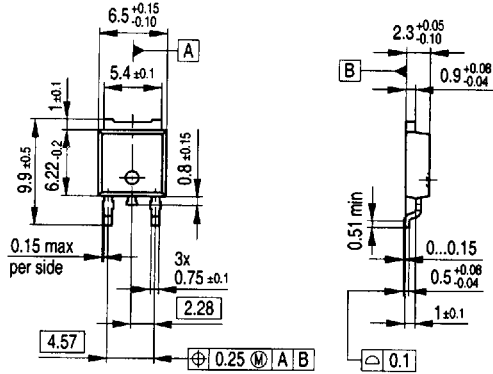
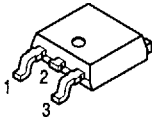


Bild 19

Figure 19

**P-TO252-3-1**

Gewicht etwa 0.38 g  
Approx. weight 0.38 g



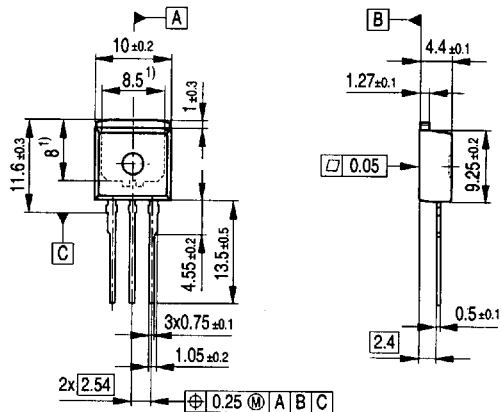
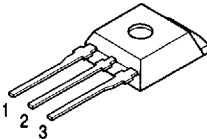
All metal surfaces tin plated, except area of cut.

GPT09051

Bild 20

Figure 20

**P-TO262-3-1/I<sup>2</sup>PAK**



1) Typical

Metal surface min. X = 7.25, Y = 7.35

All metal surfaces tin plated, except area of cut.

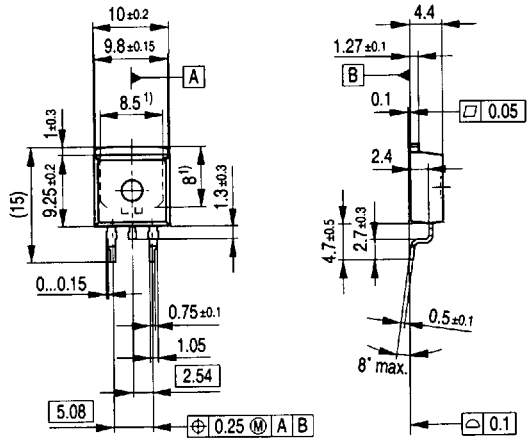
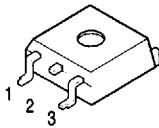
GPT09244

Bild 21

Figure 21

**P-TO263-3-2/D<sup>2</sup>PAK**

Gewicht etwa 1.38 g  
Approx. weight 1.38 g



<sup>1)</sup> Typical

All metal surfaces tin plated, except area of cut.

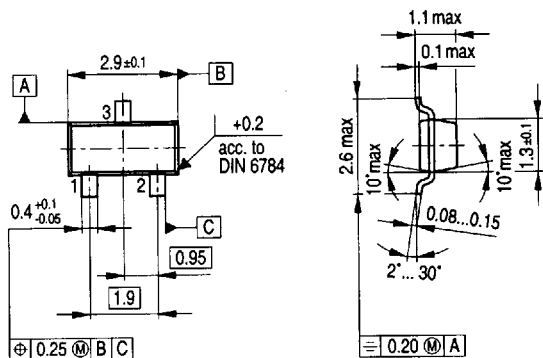
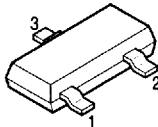
GPT09085

Bild 22

Figure 22

**SOT-23 (P-SOT23-3-1)**

Gewicht etwa 0.01 g  
Approx. weight 0.01 g



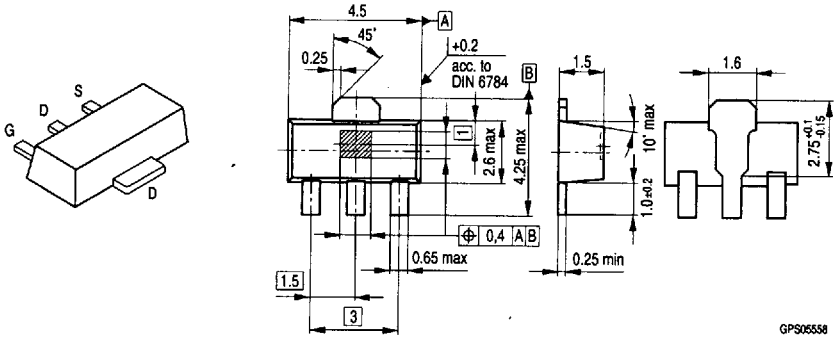
GPS05557

Bild 23

Figure 23

**SOT-89**

Gewicht etwa 0.01 g  
Approx. weight 0.01 g



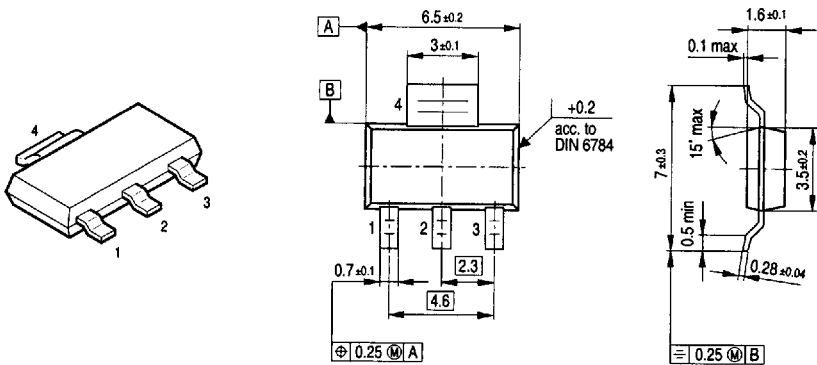
GPS05558

**Bild 24**

**Figure 24**

**SOT-223 (P-SOT223-4-1)**

Gewicht etwa 0.15 g  
Approx. weight 0.15 g



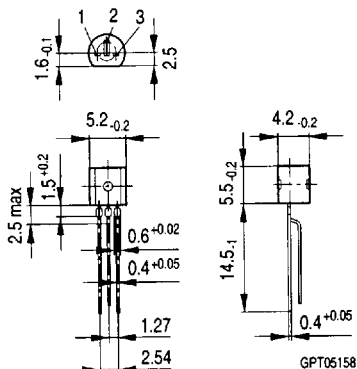
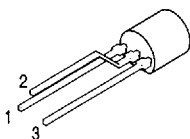
GPS05560

**Bild 25**

**Figure 25**

**TO-92**

Gewicht etwa 0.23 g  
Approx. weight 0.23 g

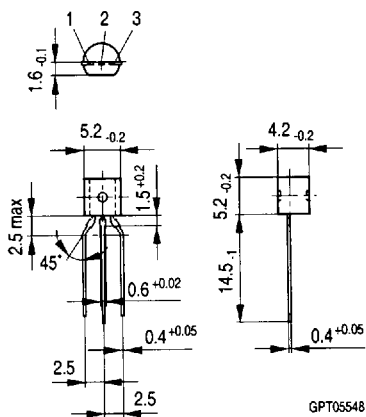
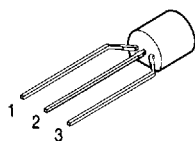


**Bild 26**

**Figure 26**

**TO-92-E6288**

Gewicht etwa 0.23 g  
Approx. weight 0.23 g



**Bild 27**

**Figure 27**

**Sorts of Packing**

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

**SMD = Surface Mounted Device**